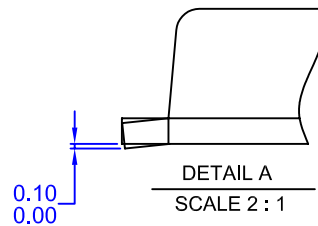
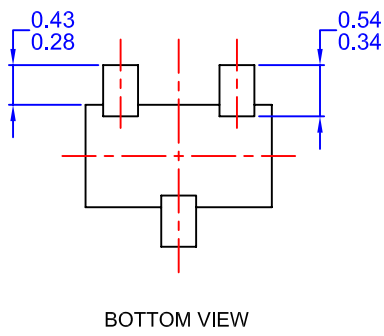
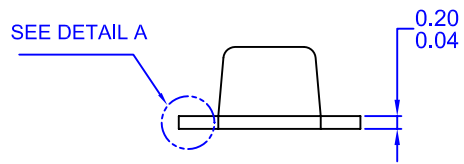
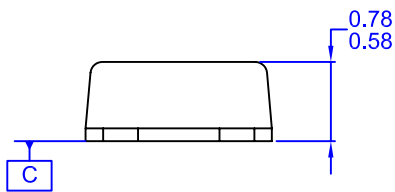
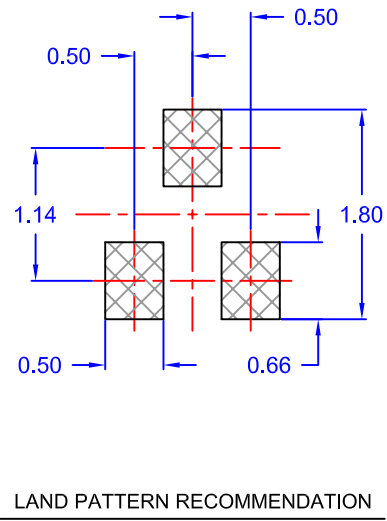
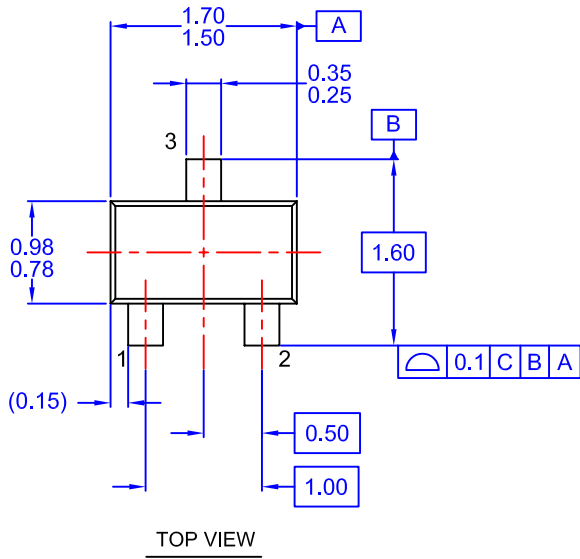


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| REVISIONS | | | | |
|-----------|-----------------------------|--------|--------|----------|
| LTR | DESCRIPTION | E.C.N. | DATE | BY/APP'D |
| A | RELEASE TO DOCUMENT CONTROL | - | 8AUG05 | OS.JEON |



NOTES:

- A) THIS PACKAGE CONFORMS TO EIAJ SC89 PACKAGING STANDARD.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DRAWING CONFORMS TO ASME Y14.5M-1994
- D) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

MAD03ArevA

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|-------------------------|--------|--|----------------------|
| APPROVALS | DATE | | BUCHEON KOREA |
| DRAWN S. W LIM | 8AUG05 | | |
| DFTG. CHK. J. S SON | 8AUG05 | | |
| ENGR. CHK. O. S JEON | 8AUG05 | | |
| | | 3LD, SC89, EIAJ-SC89, 1.2MM WIDE, SOT523F | |
| | | SCALE 1:1 | SIZE N/A |
| FORMERLY: N/A | | SHEET: 1 OF 1 | |